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Inter. with
RLE.

Docket No. 60173 (71987)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: C. Huang CONF. NO.: 7288
U.S. SERIAL NO: 10/696,198 EXAMINER: H. Trinh
FILED: October 28, 2003 GROUP: 2814
FOR: MULTI-CHIP PACKAGE DEVICE WITH HEAT SINK AND
FABRICATION METHOD THEREOF

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir/Madam:

AMENDMENT

Applicant is in receipt of the Office Action dated May 23, 2008 of the above-referenced application. Please amend the application as follows:

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 4 of this paper.